



Technical Data
Data Sheet N0667, Rev. -

Green Products

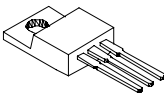
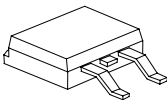
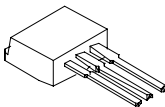
16CTQ150/16CTQ150S /16CTQ150-1 SCHOTTKY RECTIFIER

Applications:

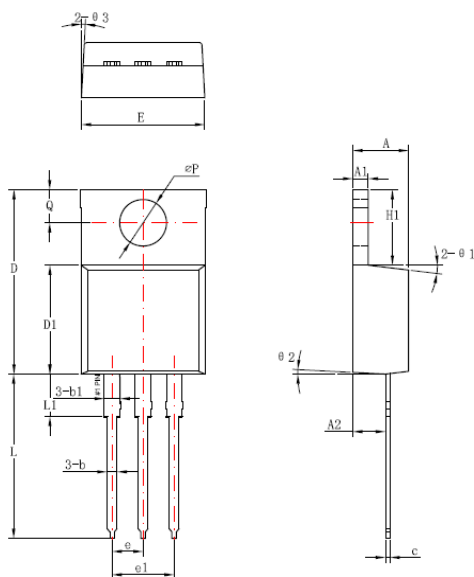
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Features:

- 175°C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

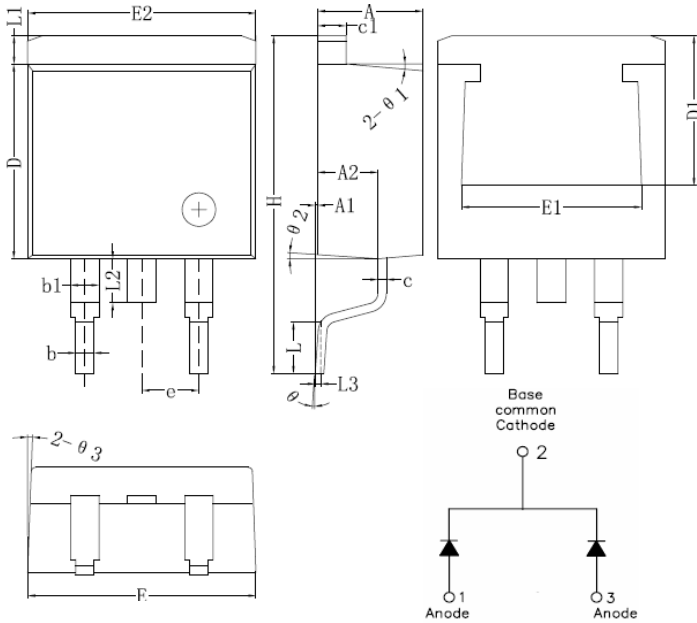
Case styles		
16CTQ150  TO-220AB	16CTQ150S  D²PAK	16CTQ150-1  TO-262

Mechanical Dimensions: In Inches / mm



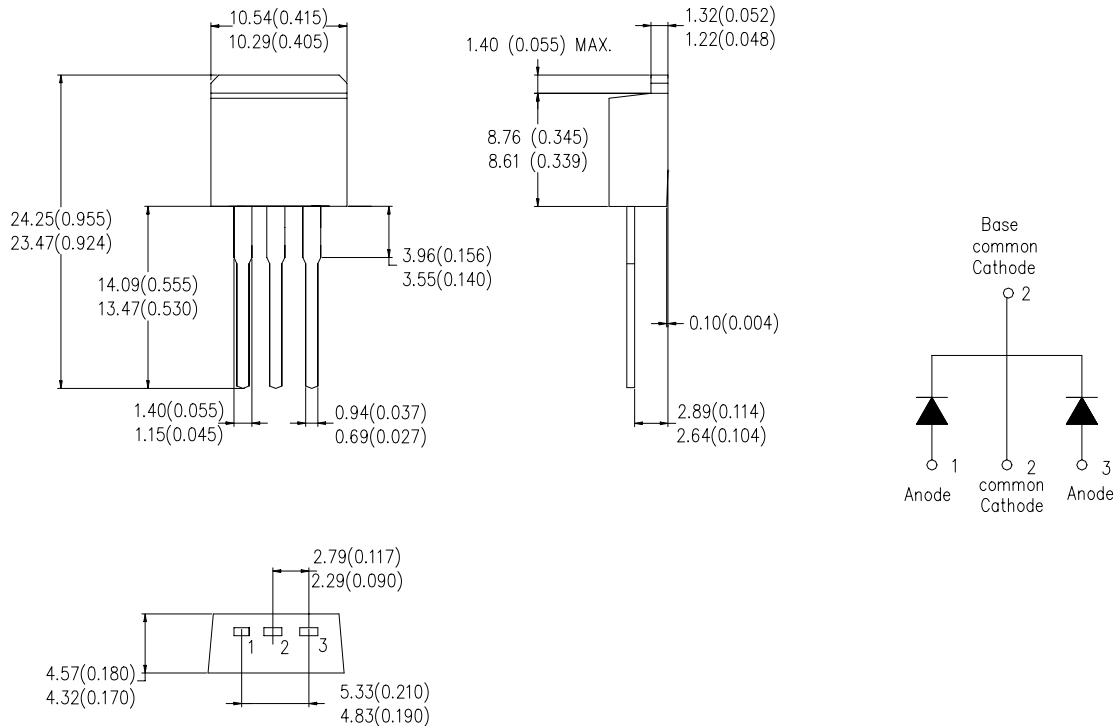
Symbol	Dimensions in millimeters		
	Min	Typical	Max
A	4.42	4.57	4.72
A1	1.17	1.27	1.37
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1		1.27	
c	0.36	0.38	0.61
D	14.94	15.24	15.54
D1	8.85	9.00	9.15
E	10.01	10.16	10.31
e		2.54	
e1		5.06	
H1	6.04	6.24	6.44
L	12.7	13.56	13.78
L1		3.5	
ΦP	3.74	3.84	4.04
Q	2.54	2.74	2.94
Q1		7°	
Q2		3°	
Q3		4°	

TO-220AB



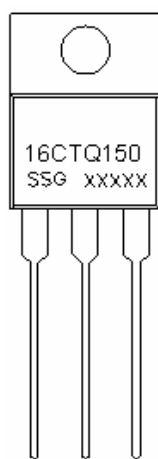
Symbol	Dimensions in millimeters		
	Min.	Typical	Max.
A	4.55	4.70	4.85
A1	0	0.10	0.25
A2	2.59	2.69	2.89
b	0.71	0.81	0.96
b1		1.27	
c	0.36	0.38	0.61
c1	1.17	1.27	1.37
D	8.55	8.70	8.85
D1	6.40		
E	10.01	10.16	10.31
E1	7.6		
E2	9.98	10.08	10.18
e		2.54	
H	14.6	15.1	15.6
L	2.00	2.30	2.70
L1	1.17	1.27	1.40
L2			2.20
L3		0.25BSC	
e	0	-	8°
e1		5°	
e2		4°	
e3		4°	

D²PAK

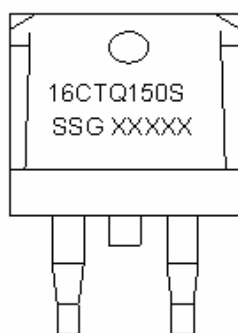


TO-262

Marking Diagram:



16CTQ150



16CTQ150S

Where XXXXX is YYWWL

16CTQ150 = Part Name
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information:

Device	Package	Shipping
16CTQ150	TO-220AB (Pb-Free)	50pcs / tube
16CTQ150S	D ² PAK (Pb-Free)	800pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Inverse Voltage	V_{RWM}	-	150	V
Max. Average Forward	$I_{F(AV)}$	50% duty cycle @ $T_C=154^\circ\text{C}$, rectangular wave form	8(per leg)	A
			16(per device)	
Max. Peak One Cycle Non-Repetitive Surge Current (per leg)	I_{FSM}	8.3 ms, half Sine pulse	276	A

Electrical Characteristics:

Characteristics	Symbol	Condition	Max.	Units
Max. Forward Voltage Drop *	V _{F1}	@ 8A, Pulse, T _J = 25 °C	0.8	V
	V _{F2}	@ 8A, Pulse, T _J = 125 °C	0.66	V
Max. Reverse Current at DC condition	I _{R1}	@V _R = rated V _R T _J = 25 °C	0.55	mA
Max. Reverse Current	I _{R2}	@V _R = rated V _R T _J = 125 °C	7.0	mA
Max. Junction Capacitance	C _T	@V _R = 5V, T _C = 25 °C f _{SIG} = 1MHz	500	pF
Typical Series Inductance	L _S	Measured lead to lead 5 mm from package body	8.0	nH
Max. Voltage Rate of Change(Rated V _R)	dv/dt	-	10,000	V/μs

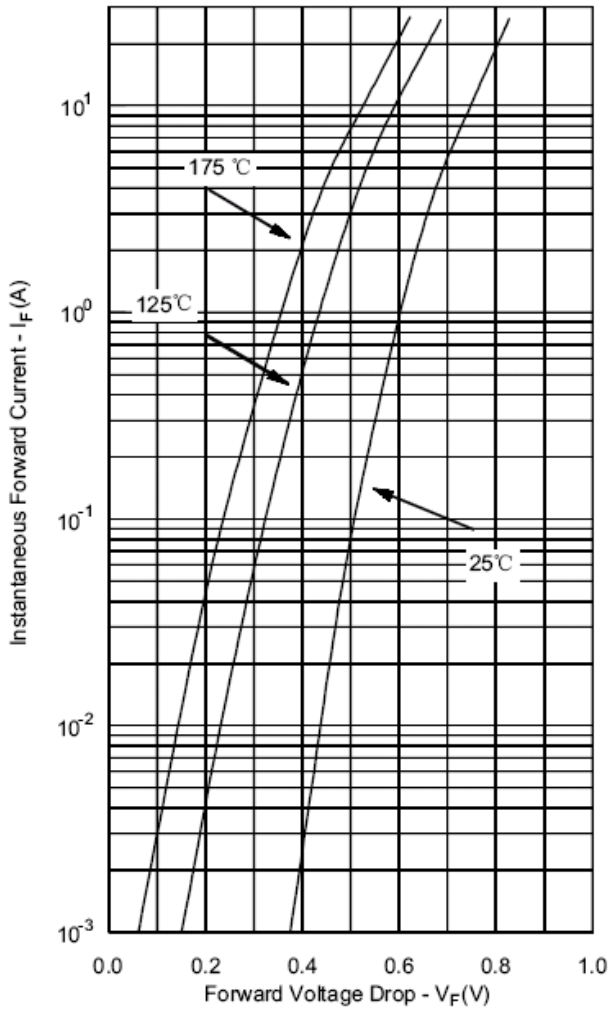
* Pulse Width < 300μs, Duty Cycle <2%

Thermal-Mechanical Specifications:

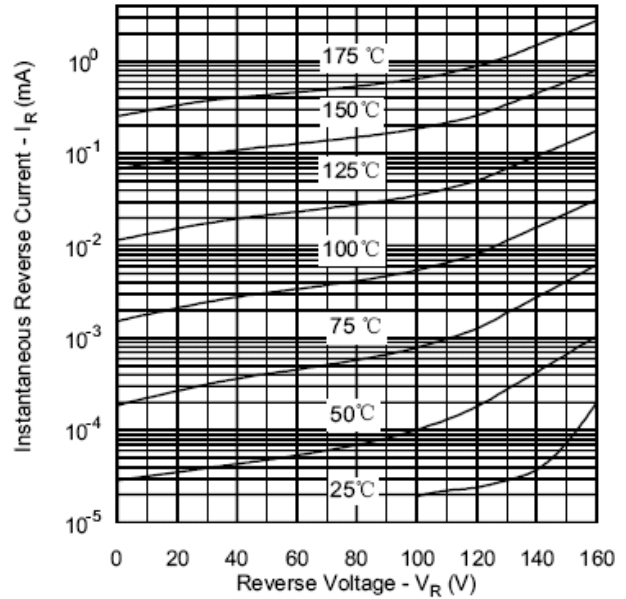
Characteristics	Symbol	Condition	Specification	Units
Max. Junction Temperature	T _J	-	-55 to +175	°C
Max. Storage Temperature	T _{stg}	-	-55 to +175	°C
Maximum Thermal Resistance Junction to Case (per leg)	R _{θJC}	DC operation	3.25	°C/W
Typical Thermal Resistance,case to Heat Sink	R _{θcs}	Mounting surface, smooth and greased	0.50	°C/W
Approximate Weight	wt	-	2	g
Case Style	TO-220AB,D ² PAK,TO-262(Suffix“s”for D ² PAK; Suffix“-1”for TO-262)			



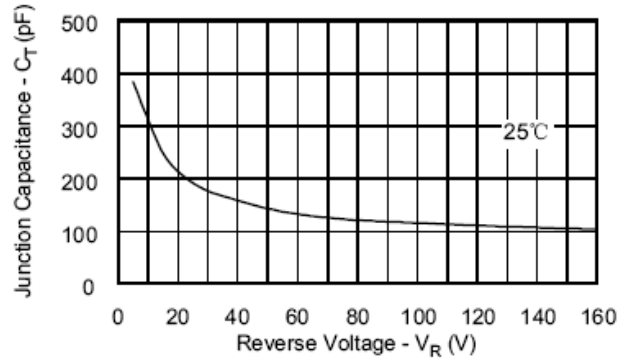
Typical Forward Characteristics



Typical Reverse Characteristics



Typical Junction Capacitance



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